COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001
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<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-01426</th>
<th>REV: E1</th>
<th>SUN: Not In VersionControl</th>
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<tbody>
<tr>
<td>M6 Assembly Bottom</td>
<td>TID #: TIDA-01426</td>
<td></td>
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<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 7/7/2017 6:09:58 PM</td>
<td>TEXAS INSTRUMENTS</td>
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